# SYSTEM AND METHOD FOR LOCATING DIES CUT FROM A SILICON WAFER ON A WAFER TABLE


## ABSTRACT OF THE INVENTION

A method for locating dies (70) cut from a silicon wafer (54) on a wafer table (14) is provided. The method includes removing a first group of dies (70) with a robot assembly (16). Wafer location data (62) is then generated from the location (66, 68) of the first group of dies (70). Continuous wafer edge coordinates are then determined from the wafer location data (62).


Figure 1

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